

# Electric Conductive Pastes for Pb-Free

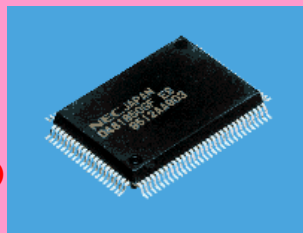
## New Silver Paste with Low Stress and Low Temp. Curable Characteristics Preventing from Oxidation of Copper Frame

### Strong Points

- 1) Low Temp. Curable (100°C, 1.5h)  
 Excellent Reflow Result Due to Restrained Oxidation of Copper Frame.
- 2) Snap Cure on Heated Stage (180°C 60sec)
- 3) Less Out Gases

### Application

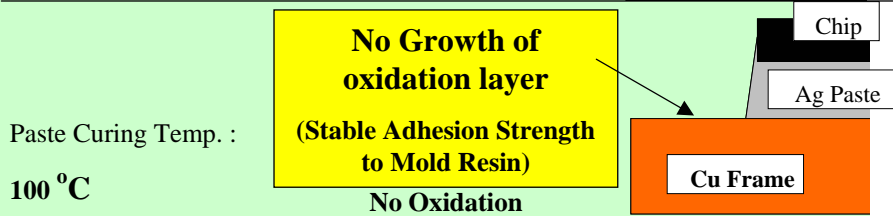
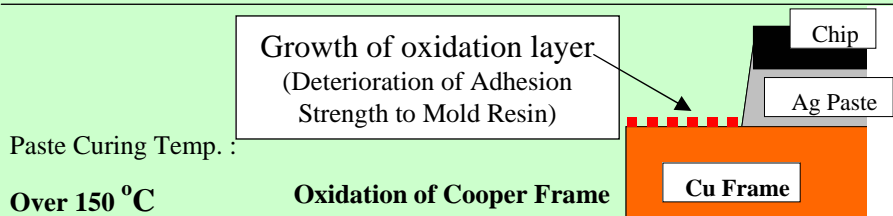
- a) Especially good for QFP,SOP etc.  
 QFP,SOP etc. (Large Die ,> 10mm\*10mm)



### Characteristic Table of New Silver Paste

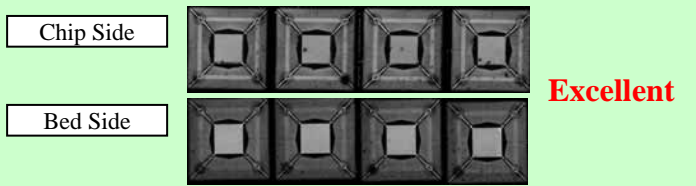
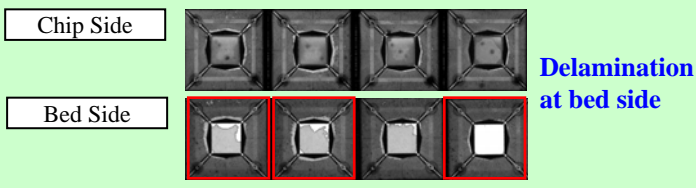
Characteristic Item		CT265L	Test Condition
Liquid Properties	Viscosity(Pa s)	60	25°C
	Tixotropic	5.0	0.5/5.0rpm
	Ash content(wt%)	76	600°C
Cured Properties	Tg(°C)	117	TMA
	Modulus(Gpa)	6.2	DMA
	CTE(ppm)	55	TMA
	Impurity(ppm)	5	Cl ion
	Impurity(ppm)	1	Na ion

### Oxidation Level of Copper Frame



### MRT/SAT(JEDEC LEVEL 2A+TCT)

#### MRT Result



### Test Condition

QFP208P(Cu) t=3.2

- a) Chip:9mm\*9mm
- b) Wire bonding condition
- c) Reliability test condition  
 Lv2A(60°C/60%RH/120H)  
 + 260°C\*3cycle Reflow  
 + TCT
- d) EMC:KE-G3000D  
 (Kyocera Chemical)